

In the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1.-4. (Cancelled)

5. (Previously presented) An electronic circuit unit comprising thin film circuit elements including conducting patterns formed on an alumina substrate, a plurality of thin film capacitors formed on the alumina substrate so as to be connected to the conducting patterns, resistors, and inductance elements and a semiconductor bare chip having a transistor wire-bonded to the conducting patterns, wherein the conducting pattern has a connection land connected to an electrode of the transistor to be grounded in a high frequency band, the capacitor has a plurality of ground capacitors grounded in the high frequency band, and one electrode of each of the plurality of capacitors is connected to the ground conducting pattern and the other electrode of each of the plurality of capacitors is connected to the connection land through the conducting patterns that are separated from each other.

6. (Original) The electronic circuit unit according to claim 5, wherein the plurality of ground capacitors are different from each other in size.

7. (Previously presented) The electronic circuit unit according to claim 5, wherein a part of the ground conducting pattern serves as the one electrode of each of the plurality of ground capacitors.

8. (Previously presented) The electronic circuit unit according to claim 6, wherein a part of the ground conducting pattern serves as the one electrode of each of the plurality of ground capacitors.

9.-17. (Cancelled)